

# **GOWIN GW1NRF Series Bluetooth FPGA User Guide**

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#### **GOWIN GW1NRF Series Bluetooth FPGA**



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#### **Revision History**

Date	Version	Description
11/12/2019	1.0E	Initial version published.

### **Purpose**

This manual contains an introduction to the GW1NRF series of Bluetooth FPGA products together with a definition of the pins, list of pin numbers, distribution of pins, and package diagrams.

#### **Related Documents**

The latest user guides are available on the GOWINSEMI Website. You can find the related documents at <a href="https://www.gowinsemi.com">www.gowinsemi.com</a>:

- 1. DS891, GW1NRF series of Bluetooth FPGA products Data Sheet
- 2. UG290, Gowin FPGA Products Programming and Configuration User Guide
- 3. UG893, GW1NRF series of Bluetooth FPGA products Package and Pinout
- 4. UG892, GW1NRF-4B Pinout

### **Terminology and Abbreviations**

The terminology and abbreviations used in this manual are as shown in Table 1-1 below. Table 1-1 Abbreviation and Terminology

Terminology and Abbreviations	Full Name
FPGA	Field Programmable Gate Array
SIP	System in Package
GPIO	Gowin Programmable IO
QN48	QFN48
QN48E	QFN48E

### Support and Feedback

Gowin Semiconductor provides customers with comprehensive technical support. If you have any questions, comments, or suggestions, please feel free to contact us directly by the following ways.

Website: <a href="mailto:www.gowinsemi.com.cn">www.gowinsemi.com.cn</a></a><a href="mailto:com.cn">cn</a><a href="mailto:com.cn">com.cn</a><a href="mailto:com.cn">com.cn</a><a

#### Overview

The GW1NRF series of FPGA products are the first generation products in the LittleBee® family and represent one form of SoC FPGA. The GW1NRF series of FPGA products integrate 32 bits hardcore processor and support Bluetooth 5.0 Low Energy radio. They have abundant logic units, IOs, built-in B-SRAM and DSP resources, power management module, and security module. The GW1NRF series provides low power consumption, instant on, low cost, non-volatile, high security, various packages, and flexible usage.

#### **PB-Free Package**

The GW1NRF series of Bluetooth FPGA products are PB free in line with the EU ROHS environmental directives. The substances used in the GW1NRF series of Bluetooth FPGA products are in full compliance with the IPC-1752 standards.

#### Package, Max. User I/O Information, and LVDS Paris

Table 2-1 Package, Max. User I/O Information, and LVDS Paris

Package	Pitch (mm)	Size (mm)	GW1NRF-4B
QN48	0.4	6 x 6	25(4)
QN48E	0.4	6 x 6	25(4)

#### Note!

- In this manual, abbreviations are employed to refer to the package types. See 1.3Terminology and Abbreviations.
- See GW1NRF series of Bluetooth FPGA Products Data Sheet for more details.
- The JTAGSEL\_N and JTAG pins cannot be used as I/O simultaneously. The data in this table is when the loaded four JTAG pins (TCK, TDI, TDO, and TMS) are used as I/O;

#### **Power Pin**

#### Table 2-2 Other Pins in the GW1NRF Series

VCC	VCCO0	VCCO1	VCCO2
VCCO3	VCCX	VSS	

## **Pin Quantity**

**Quantity of GW1NRF-4B Pins** 

Table 2-3 Quantity of GW1NRF-4BPins

Pin Type		GW1NRF-4B	
		QN48	QN48E
	BANK0	9/4/0	9/4/0
I/O Single end / Differential pair / L	BANK1	4/1/1	4/1/1
VDS1	BANK2	8/4/3	8/4/3
	BANK3	4/1/0	4/1/0
Max. User I/O 2		25	25
Differential Pair		10	10
True LVDS output	True LVDS output		4
VCC	vcc		2
VCCX		1	1
VCCO0/VCCO33		1	1
VCCO1/VCCO23		1	1
VSS		2	1
MODE0		0	0
MODE1		0	0
MODE2		0	0
JTAGSEL_N		1	1

#### Note!

- 1. The number of single end/ differential/LVDS I/O includes CLK pins and download pins;
- 2. The JTAGSEL\_N and JTAG pins cannot be used as I/O simultaneously. The data in this table is when the loaded four JTAG pins (TCK, TDI, TDO, and TMS) are used as I/O; When mode [2:0] = 001, JTAGSEL\_N and the four JTAG pins (TCK, TDI, TDO, and TMS) can be used as GPIO simultaneously, and the Max. user I/O plus one.
- 3. Pin multiplexing.

### **Pin Definitions**

The location of the pins in the GW1NRF series of Bluetooth FPGA products varies according to the different packages. Table 2-4 provides a detailed overview of user I/O, multi-function pins, dedicated pins, and other pins.

Table 2-4 Definition of the Pins in the GW1NRF series of Bluetooth FPGA products

Pin Name	I/O	Description
Max. User I/O		

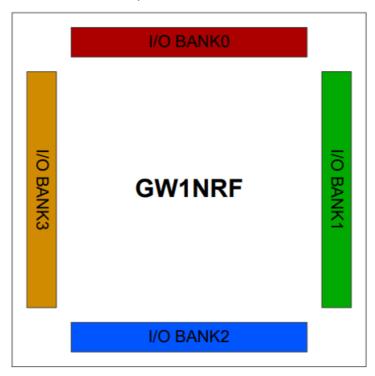
		[End] indicates the pin location, including L(left) R(right) B(b ottom), and T(top)	
IO[End][Row/Column Number][A/B]	I/O	[Row/Column Number] indicates the pin Row/Column numb er.If [End] is T(top) or B(bottom), the pin indicates the colum n number of the corresponding CFU. If [End] is L(left) or R(right), the pin indicates the Row number of the corresponding CFU.  [A/B] indicates differential signal pair information.	
Multi-Function Pins			
IO[End][Row/Column Number][A/B]/MMM		/MMM represents one or more of the other functions in addition to being general purpose user I/O. These pins can be used as user I/O when the functions are not used.	
RECONFIG_N	I, internal weak	Start new GowinCONFIG mode when low pulse	
READY	I/O	High level indicates the device can be programmed and configured currently  Low level indicates the device cannot be programmed and configured currently	
DONE	I/O	High level indicates successful program and configure  Low level indicates incomplete or failed to program and configure	
FASTRD_N /D3	I/O	In MSPI mode, FASTRD_N is used as Flash access speed port. Low indicates high-speed Flash access mode; high indicates regular Flash access mode.  Data port D3 in CPU mode	
MCLK /D4	I/O	Clock output MCLK in MSPI mode Data port D4 in CPU mode	
MCS_N /D5	I/O	Enable signal MCS_N in MSPI mode, active-low  Data port D5 in CPU mode	
MI /D7	I/O	MISO in MSPI mode: Master data input/Slave data output  Data port D7 in CPU mode	
MO /D6	I/O	MISO in MSPI mode: Master data output/Slave data input  Data port D6 in CPU mode	

SSPI_CS_N/D0	I/O	Enable signal SSPI_CS_N in SSPI mod, active-low, Internal Weak Pull Up  Data port D0 in CPU mode
SO/D1	I/O	MISO in MSPI mode: Master data input/Slave data

#### I/O BANK Introduction

There are four I/O Banks in the GW1NRF series of FPGA products. The I/O BANK Distribution of the GW1NRF series of Bluetooth FPGA products is as shown in Figure 2-1.

Figure 2-1GW1NRF series of Bluetooth FPGA products I/O Bank Distribution



This manual provides an overview of the distribution view of the pins in the GW1NRF series of Bluetooth FPGA products. The four I/O Banks that form the GW1NRF series of Bluetooth FPGA products are marked with four different colors.

Various symbols are used for the user I/O, power, and ground. The various symbols and colors used for the various pins are defined as follows:

- " denotes the I/O in BANK0. The filling color changes with the BANK;
- denotes the I/O in BANK1. The filling color changes with the BANK;
- " **🔁** "
- "denotes the I/O in BANK2. The filling color changes with the BANK;
- "denotes the I/O in BANK3. The filling color changes with the BANK;
- "denotes VCC, VCCX, and VCCO. The filling color does not change;

- " denotes VSS, the filling color does not change;
- denotes NC;
- " denotes BLE, the filling color does not change.

### **View of Pin Distribution**

View of GW1NRF-4B Pins Distribution

### **View of QN48 Pins Distribution**

Figure 3-1 View of GW1NRF-4B QN48 Pins Distribution (Top View)

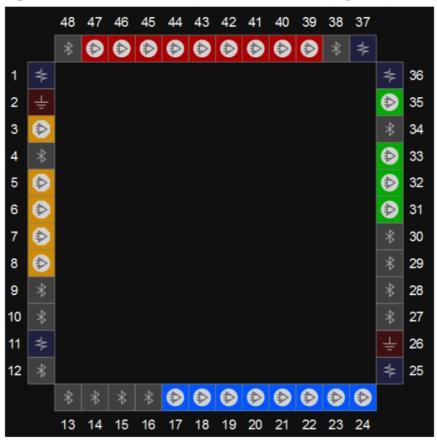


Table 3-1 Other pins in GW1NRF-4B QN48

VCC	11,37
VCCX	36
VCCO0/VCCO3	1
VCCO1/VCCO2	25
VSS	26,2

**View of QN48E Pins Distribution** 

Figure 3-2 View of GW1NRF-4B QN48E Pins Distribution (Top View)

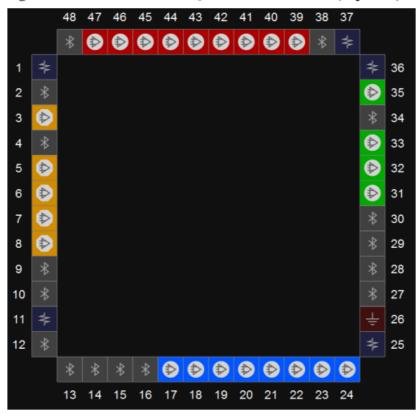


Table 3-2 Other pins in GW1NRF-4B QN48

VCC	11,37
VCCX	36
VCCO0/VCCO3	1
VCCO1/VCCO2	25
VSS	26

### **Package Diagrams**

### QN48 Package Outline (6mm x 6mm)

	MILLIMETER		
SYMBOL	MIN	NOM	MAX
Α	0.75	0.85	0.85
A1		0.02	0.05
b	0.15	0.20	0.25
С	0.18	0.20	0.23
D	5.90	6.00	6.10
D2	4.10	4.20	4.30
е	0.40 BSC		
Ne	4.40BSC		
Nd	4.40BSC		
E	5.90	6.00	6.10
E2	4.10	4.20	4.30
L	0.35	0.40	0.45
h	0.30	0.35	0.40
L/F		•	
MIL	177*177		

### **Documents / Resources**



### References

- \* Home GOWIN Semiconductor
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- \* Home|GOWIN Semiconductor